

IN THE CLAIMS

Please amend the claims as follows:

1. (Currently Amended) A ceramic substrate having: a heating element composed of one or more circuit(s) on a surface thereof or inside thereof; and a through hole configured to receive a lifter pin or a supporting pin inserted therein being made in the ceramic substrate, wherein said heating element circuit is formed in the range of 20 mm or less from the inner wall of said through hole.
2. (Previously Presented) The ceramic substrate according to claim 1, wherein said heating element circuit is formed in the range of 0.1 to 20 mm from the inner wall of said through hole.
3. (Previously Presented) The ceramic substrate according to claim 1, wherein the thickness of said ceramic substrate is over 1.5 mm.
4. (Previously Presented) The ceramic substrate according to claim 2, wherein the thickness of said ceramic substrate is over 1.5 mm.